

poor reliability. Furthermore, the packaging thickness is minimum and the heat radiation is improved.

Abstract:

Please delete the Abstract in its entirety and replace it with the following.

ABSTRACT

A semiconductor packaging device provides a carrier having at least a portion configured for containing a chip. The chip, affixing to the portion with sidewall, has a back surface an active surface, which multitudes of bonding pads are on the active surface. One insulating layer on the active surface and carrier has multitudes of conductive holes corresponding to the first bonding pads. A multi-layer structure on the insulating layer is configured for providing electrical connection to the conductive holes. Another insulating layer, affixed on one of the carrier and the multi-layer structure, has another conductive holes electrically connected to the conductive holes. Multitudes of solder balls, on at least one of the carrier and latter insulating layer, electrically connect the latter conductive holes.